

plastic, thermal enhanced quad; flat package; 80 terminals; 0.65 mm pitch; 14 mm x 14 mm x 2.3 mm body

13 December 2016

Package information

1. Package summary

Terminal position code Q (quad)

Package type descriptive code HQFP

Package type industry code HQFP80

Package style descriptive code HQFP (thermal enhanced quad flat package)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date 6-6-2016

Manufacturer package code 98ASB42846B

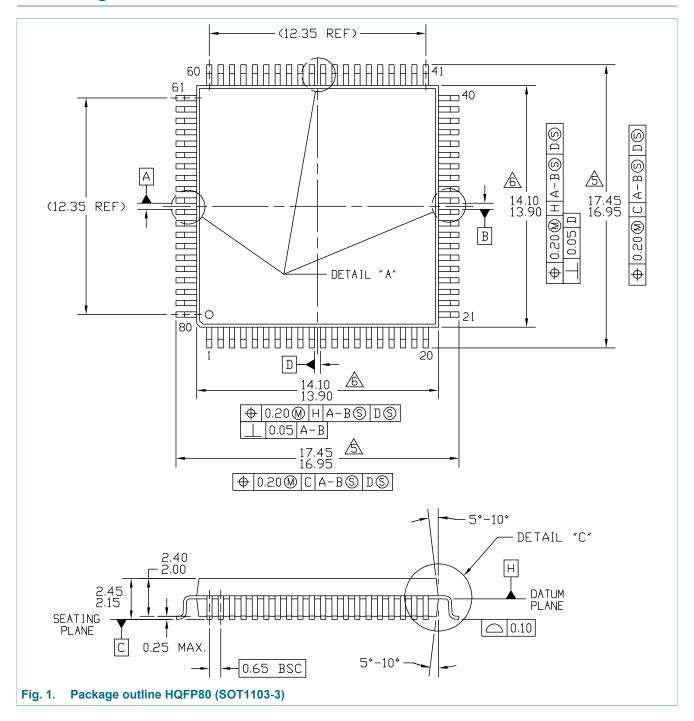
Table 1. Package summary

Symbol	Parameter	Min	Тур	Nom	Max	Unit
D	package length	13.9	-	14	14.1	mm
E	package width	13.9	-	14	14.1	mm
Α	seated height	2.15	-	2.3	2.45	mm
е	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	80	-	

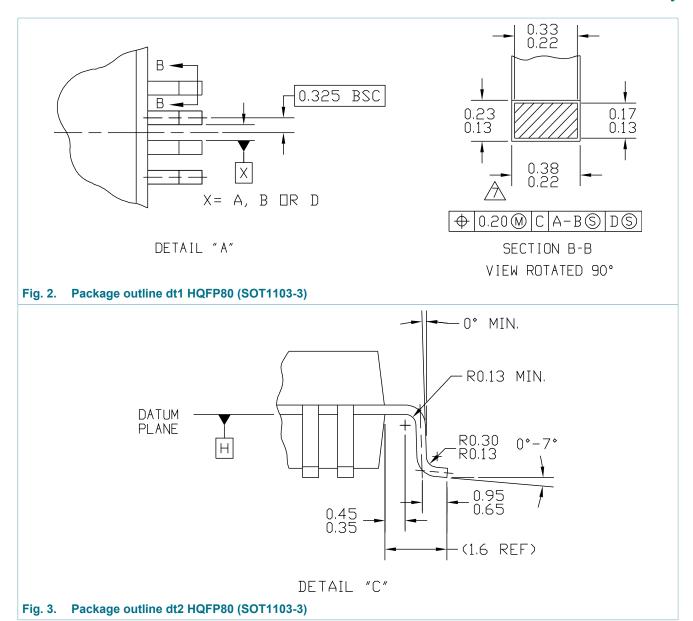


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2. Package outline



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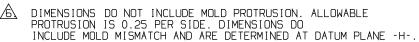


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NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
- 4. DATUMS A-B AND -D- TO BE DETERMINED AT DATUM PLANE -H-.





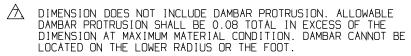


Fig. 4. Package outline note HQFP80 (SOT1103-3)

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3. Legal information

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Date of release: 13 December 2016